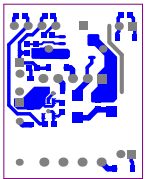
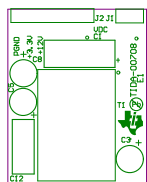


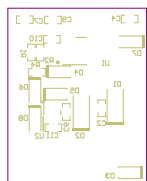
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00708		
PLOT NAME = Top Layer	GENERATED : 3/17/2016 2:39:29 PM	TEXAS INSTRUMENTS	



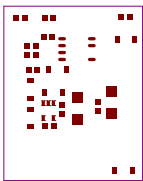
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00708		
PLOT NAME = Bottom Layer	GENERATED : 3/17/2016 2:39:29 PM	TEXAS INSTRUMENTS	



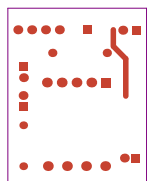
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00708		
PLOT NAME = Top Silkscreen Overlay	GENERATED : 3/17/2016 2:39:30 PM	TEXAS INSTRUMENTS	



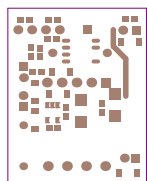
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00708		
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 3/17/2016 2:39:30 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: TIDA-00708		
PLOT NAME = Bottom Paste Mask Print	GENERATED : 3/17/2016 2:39:30 PM	TEXAS INSTRUMENTS	

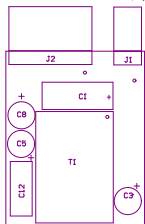


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00708		
PLOT NAME = Top Solder Mask Print	GENERATED : 3/17/2016 2:39:31 PM	TEXAS INSTRUMENTS	



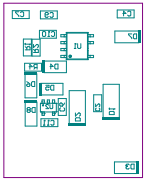
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00708		
PLOT NAME = Bottom Solder Mask Print	GENERATED : 3/17/2016 2:39:31 PM	TEXAS INSTRUMENTS	

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In VersionControl
IGNORE -> M5 Assembly Top	TID #: TIDA-00708		
PLOT NAME = M5 Assembly Top	GENERATED : 3/17/2016	2:39:31 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT [No Variants]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00708	REV: E1	SWN REV: Not In VersionControl
M8 Assembly Bottom	TID #: TIDA-00708 IGNORE ->		
PLOT NAME = M8 Assembly Bottom	GENERATED : 3/17/2016 2:38:31 PM	TEXAS INSTRUMENTS	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				///
2	Top Solder	Solder Resist	0.40mil	3.5	///
3	Top Layer	Copper	1.40mil		///
4	Dielectric	FR-4 High Tg	59.20mil	4.8	///
5	Bottom Layer	Copper	1.40mil		///
6	Bottom Solder	Solder Resist	0.40mil	3.5	///
7	Bottom Overlay				///

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
25.45MM X 32MM

Number of Layers : 2
 MIN. TRACK WIDTH: 15_MIL
 MIN. CLEARANCE: 8_MIL
 MIN. VIA PAD SIZE: 36_MIL

MINIMUM ANNULAR RING 0.228mm (9MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5_MIL, HOLES +/- 3_MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____

THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENG) ENEPG
 IMM. TIN/SILVER OR EQUIV OTHER _____

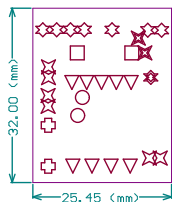
ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES VIA TENCING: YES NO
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SILK

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Physical Length	Route Path Length
*x	2	30.00mil (0.76200mm)	NPTH	Slot	150.00mil (3.81000mm)	120.00mil (3.04800mm)
*	1	30.00mil (0.76200mm)	NPTH	Slot	300.00mil (7.62000mm)	270.00mil (6.85800mm)
o	2	18.00mil (0.45700mm)	PTH	Round		
o	2	31.50mil (0.80000mm)	PTH	Round		
x	6	33.46mil (0.85000mm)	PTH	Round		
□	2	35.43mil (0.90000mm)	PTH	Round		
*	7	40.16mil (1.02000mm)	PTH	Round		
▽	9	46.06mil (1.17000mm)	PTH	Round		
	31 Total					

Drill Table
 FOR 18MIL DRILL +/-18MIL
 FOR PTH +/- 3MIL
 FOR NPTH +/- 2MIL
 It is not an impedance control board.



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00708	REV: E1	SUN REV: Not In Version Control
LAYER NAME = Drill Drawing	TID #: TIDA-00708		
PLOT NAME = Drill Drawing For (Bottom Layer) (DATE) (USER): 3/17/2016 2:39:32 PM	TEXAS INSTRUMENTS		

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TEXAS INSTRUMENTS

PROJECT TITLE:
5W Auxiliary Supply for AC-DC Power Converters

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00708_E1.PcbDoc

ENGINEER:
Neha Nain

LAYOUT BY:
Manjunatha T N

ALTIUM DESIGNER VERSION:
14.3.14.34663

SCALE: 1.00

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